



ATSC 2018

9th Asian Thermal Spray Conference

November 16-18, 2018
Nanyang Technological University
Singapore

Call for Papers

Organized by

Institute of Materials (East Asia)
Asian Thermal Spray Society

Conference Chair

Khiam Aik KHOR (Nanyang Technological University)/Singapore

International Advisory Board

Chang-Jiu LI (Xi'an Jiaotong University)/China
Eungsun BYON (Korea Institute of Materials and Science)/Korea
Kazuhiro OGAWA (Tohoku University)/Japan
Masahiro FUKUMOTO (Toyohashi University of Technology)/Japan

Website of ATSC2018: <http://www.materials.org.sg/ATSC2018/>

Scope of Conference

We would like to invite you to 9th Asian Thermal Spray Conference (ATSC 2018), which will be held in Nanyang Technological University, Singapore on November 16-18, 2018. ATSC is currently held two times every three years except the year when the International Thermal Spray Conference is held in Asian countries. The purpose of this conference is to bring regularly all researchers involved in R&D, technicians in thermal spray job shops, manufacturers of thermal spray materials and equipment, managers of the companies involving in thermal spraying in Asian area to share the latest advancements of thermal spray technology. It is also expected that the conference will inspire and nurture young engineers and researchers in the region through international experiences.

Important Dates

Abstract due	June 30, 2018
Acceptance of abstract	July 31, 2018
Manuscript submission for proceedings	September 30, 2018
Conference	November 16-18, 2018

The Technical Program at the 9th ATSC will address diverse aspects related to thermal spray science and technology, ranging from fundamental research to industrial applications. The topics of interest include, but are not restricted to, any of the several themes listed below:

- Cold Spray/Kinetic Spray
- Solution and Suspension based Spray Processes
- Advances in Thermal Spray Processes
- Hybrid Spray Processes
- Thermal Barrier Coatings

- Repair & Refurbishment
- Wear & Corrosion Protection
- Novel Functional Applications
- Modelling & Simulation
- Process Control & Diagnostics

- Processing-Structure-Property correlations
- Advanced Characterization of Coatings
- Mechanical Properties of Coatings
- Environmental/Occupational Safety
- Advanced Material Systems

Submission of Abstract

You are invited to submit electronically abstracts of 150-200 words before the deadline to Dr. Yu Ligen (MLGYU@ntu.edu.sg). The abstract should start with TITLE of PAPER (in CAPITALS, center justified and bold) followed by full names of participating authors, their affiliation, and correspondence for mailing and e-mail address.

Sample Abstract:

Paper Title in both upper and lower case, alignment: centred Maximum 2 lines, Font: Times New Roman 12 bold.

Z. AUTHOR1, Y. AUTHOR2 and X. AUTHOR3

Affiliation1, 12 points, Your University, Name of Your Country

W. AUTHOR4

Affiliation2, 12 points, Your University, Name of Your Country

E-mail: name@corresponding.author.edu

Text begins here. Times New Roman, font size 10 points. Maximum length 200 words.

Publication

Two-page extended abstracts of all the accepted papers to be presented at ATSC 2018 will be included in a conference proceeding available at the conference. Selected papers will appear as a special issue of Journal of Thermal Spray Technology dedicated to ATSC 2018.

Registration

The Registration Fee structure for participation in ATSC 2018 is as follows:

	Category	Foreign Participants	Domestic Participants
Early-Bird Registration <i>(register before September 01, 2018)</i>	Oral Presentation / Poster Presentation/ Participation	300 USD	400 SGD
	Students	200 USD	300 SGD
On-Site Registration	Oral Presentation / Poster Presentation/ Participation	350 USD	450 SGD
	Students	250 USD	350 SGD

Exhibition

Information about the exhibition will appear on the website.

Conference Secretariat

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Nanyang Technological University,

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Mark your calendar today...Looking forward to seeing you in Singapore!